

Abstract of the Disclosure

**[0052]** A method for depositing a metal on a substrate is provided. The metal is deposited by sequentially applying a electrodeposition pulse followed by an electrodisolution pulse to the substrate. After each electrodisolution pulse an before the next electrodeposition pulse there is provided at least one time interval of zero electrical voltage or current, also known as an "off-time", between the pulses. The first two electrodeposition pulses should preferably have the same time durations. Thereafter, the time durations of subsequent electrodeposition pulses are gradually decreased to provide a void-free and seam-free deposition of metal in high aspect ratio features.

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